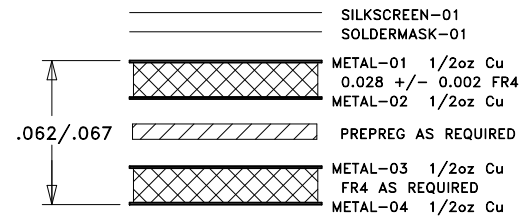


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REVISION				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1	ENGINEERING RELEASE	06/04/09	M.LYONS

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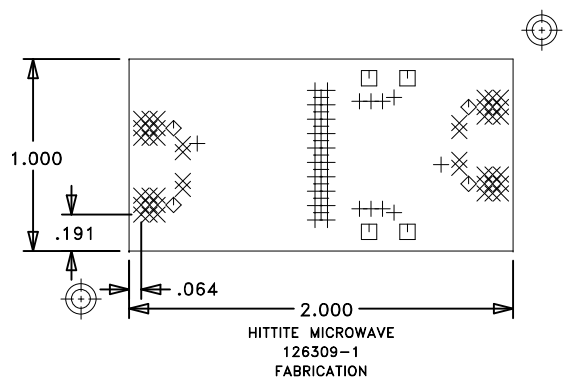
NOTES:
UNLESS OTHERWISE SPECIFIED:

1. MATERIAL: MULTILAYER FR4 PER STACKUP.
2. FINISH: GOLD PLATE PER ASTM B-488, TYPE III, CODE A, 8 TO 40 MICROINCHES, OVER NICKEL PER QQ-N-290, 100 MICROINCHES MINIMUM.
3. PLATED THRU HOLES: .001" MINIMUM WALL THICKNESS.
4. HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
5. ALL HOLES TO BE LOCATED WITHIN ± 0.003 " OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
6. FRONT TO BACK REGISTRATION ± 0.003 " MAX.
7. BOARD WARPAGE: < 0.010 " PER LINEAR INCH.
8. SILKSCREEN TOPSIDE ONLY WITH WHITE EPOXY INK.
9. PLATING THICKNESS $.002 \pm 0.0005$ FOR METAL-01 AND METAL-04.
10. SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ± 0.004 MAX.
11. REMOVE METAL BURRS FROM EDGE OF PCB AFTER PANEL SEPARATION.
12. ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.
13. "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
14. MANUFACTURE PER IPC-600 CLASS 2.

SPECIAL REQUIREMENTS:

15. METAL-01 CRITICAL LINE WIDTH = $.020 \pm 0.001$ " ADJUST PROCESS TO ACHIEVE WIDTH.

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SIZE	QTY	SYM	PLATED	TOL
14	39	+	YES	+/-3
18	44	X	YES	+/-3
43	4	□	YES	+/-3
80	4	◇	YES	+/-3

PROPRIETARY TO HITTITE MICROWAVE CORPORATION

UNLESS OTHERWISE SPECIFIED:	DWN BY:
DIMENSIONS ARE IN INCHES (MM)	MARTIN LYONS 05/28/09
DRAWING PRACTICES PER MIL-STD-100	ENGINEER:
TOLERANCES:	SELEN KILINC
.XX +/- 0.010	
.XXX +/- 0.005	
.XXXX +/- 0.002	
ANGLES +/- .5 DEG	

 HITTITE MICROWAVE CORPORATION 20 Alpha Road Chelmsford, MA 01824			
TITLE PCB, EVAL HMC754S8G			
SIZE A	CODE ID NO. 1CN88	DRAWING NO. 126309	REV 1
SCALE:	WT	SHEET 1 of 1	

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